Contact Name  Title - Contact Phone - Contact*  Product-Env-Stewards Authorized Representative* Product-Env-Stewards Product Enviro Compliance Phone - Representative* Product-Env-Stewards Product-Env-Stewards@onsemi.com Requester Item Number Mfr Item Number Mfr Item Name Effective Date Version Manufacturing Site Weight* UOM Un	ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.			der both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with low level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
Company name* Company name* Company name* Company name* Contact Name Contact Name Title - Contact* Product-Env-Stewards Authorized Representative* Title - Representative Tompliance NA Product-Env-Stewards Product-Env-Stewards Product-Env-Stewards Product-Env-Stewards One Product-Env-Steward	752-21.1										als and Mfg	Informati	ion		
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Product-Env-Stewards withorized Representative* Product-Env-Stewards Product Enviro Compliance Product-Env-Stewards Product-Env-Steward	Company name*			Company unique ID			J	Unique ID Authority				Response Date*			
Product Enviso Compliance Unthorized Representative* Title - Representative Product Enviro Compliance Product Enviro Compliance Product Enviro Compliance Product Enviro Compliance NA Product Enviro Stewards @ onsemi.com NA	onsemi											2025-06-04			
Authorized Representative*  Product Enviro Compliance Requester Item Number Requester Item Number Requester Item Number Representative  Product Enviro Compliance NA Requester Item Number Representative  Product Enviro Compliance NA Requester Item Number Requester Item Number Representative*  Product Enviro Compliance NA Requester Item Number Representative*  Product-Env-Stewards@onsemi.com  Manufacturing Site Weight* UOM Un PANJITFG 92.0 mg Ear  Manufacturing Proccess Information  Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cycles Matte Tin (Sn) - annealed CU Alloy 1 260 C 30 seconds 3	ontact Name			Title - Contact			I	Phone - Contact*				Email - Contact*			
Product Envisor Compliance Requester Item Number Mfr Item Number Mfr Item Number Mfr Item Name Effective Date Version Manufacturing Site Weight* UOM Un PANJITFG 92.0 mg Each Manufacturing Process Information  Terminal Plating / Grid Array Material Terminal Base Alloy Terminal	Product-Env-Stewa	rds		Product Enviro Compliance			1	NA				Product-Env-Stewards@onsemi.com			
Requester Item Number	uthorized Represer	ntative*		Title - Representative			I	Phone - Representative*			Email - Representative*				
FSV15120V 15 A 120V Schottky 2025-06-04 PANJITFG 92.0 mg Each Comments Part of the part of Reflow Cycles and the part of Reflo	Product-Env-Stewar	rds		Product Enviro Compliance			]	NA				Product-Env-Stewards@onsemi.com			
Manufacturing Proccess Information  Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 MSL Rating Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cycles  Matte Tin (Sn) - annealed CU Alloy 1 260 C 30 seconds 3	Requester	r Item Number	Mfr Item Number		Mfr Item Name			Effective Date	Version Manufacturing Site		W	eight*	UOM	Unit Type	
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Matte Tin (Sn) - annealed CU Alloy 1 260 C 30 seconds 3 comments				arminal Reso	Alloy	STD 020 MSI	Pating	Dank Prog	ess Rody T	amparatur	a May Time at Pools	Tamparatur	Numb	per of Paflow Cya	lac
Comments					Alloy J-S	31D-020 MSL	. Kaung		ess body 1	T *				bei of Kellow Cyc	108
	•	i (Sii) - aimeaieu	C	O Alloy	1			200		IC	30	seconds			
ver 1 - maximum ume at peak temperature during soldering is 10-50 seconds		me at neels tomporetur	o dunina sal	domina ia 10. 1	10 seconds										
or more information regarding material composition please refer to page 3															

RoHS Material Composition Declaration			Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU  RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier neter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provid										
RoHS Declaration * 4 - Item(s	) does not contain RoHS restricted substance	s per the definition above except for selected exemp	tions Supplier Acceptance	* Accepted						
Exemption: 7a: Lead in high melting temper	erature type solders (i.e. lead based solder	alloys containing 85% by weight or more lead).								
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.										
Supplier Digital Signature Ra	astislav Drska	-En								

## **Homogeneous Material Composition Declaration for Electronic Products**

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

<b>Homogeneous Material</b>	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Clip	4.942	mg	Supplier	Zinc (Zn)	7440-66-6		0.0059	mg
			Supplier	Iron (Fe)	7439-89-6		0.1161	mg
			Supplier	Copper (Cu)	7440-50-8		4.8184	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0015	mg
Die	9.594	mg	Supplier	Silicon (Si)	7440-21-3		9.594	mg
Die Attach Solder	4.165	mg	Supplier	Silver (Ag)	7440-22-4		0.1041	mg
			A	Lead (Pb)	7439-92-1	7a	3.8526	mg
			Supplier	Tin (Sn)	7440-31-5		0.2083	mg
Lead Frame	30.081	mg	Supplier	Chromium (Cr)	7440-47-3		0.0602	mg
			Supplier	Manganese (Mn)	7439-96-5		0.2406	mg
			В	Nickel (Ni)	7440-02-0		12.3332	mg
			Supplier	Iron (Fe)	7439-89-6		17.447	mg
Mold Compound-Black	43.217	mg		Metal Hydroxide	proprietary data		1.5126	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		3.4574	mg
			Supplier	Carbon Black (C)	1333-86-4		0.2161	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		34.5736	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		3.4574	mg
Plating	0.001	mg	Supplier	Tin (Sn)	7440-31-5		0.001	mg